

Amendments to the Abstract:

~~An object of the present invention is to provide a~~ A technology is provided that can seal the opening of the interposer ~~by in a wiring board using a~~ transfer mold with the leak of the insulating resin from the above-described opening prevented. A mold die ~~comprising is used which includes~~ a first die having a recess in a predetermined form and a second flat die, ~~the above-described mold die being for disposing the above-described.~~ The first die is disposed on a surface of a wiring board which has a plurality of openings and ~~bears on which~~ a semiconductor chip is mounted via an elastic material, ~~which surface bears the above-described semiconductor chip, and for disposing the above-described.~~ The second die is disposed on a back surface of the above-described surface of the above-described wiring board opposite the surface on which bears the above-described semiconductor chip is mounted. The mold is used, and for sealing with an insulating resin ~~a the~~ periphery of the above-described semiconductor chip and at least one of the above-described openings of the above-described wiring board, wherein the above-described second die ~~comprises has~~ a protrusion around an area overlapping the above-described opening to be sealed with the above-described insulating resin.

(Selected Figure) Fig. 3